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ABSTRACT

To reduce conductor resistance and improve heat dissipation. A substrate includes a first substrate having a first surface on which an element is to be mounted, a second surface located opposite the first surface, and a first side surface connecting the first surface and the second surface, a second substrate larger than the first substrate and having a third surface supporting the first substrate and a fourth surface located opposite the third surface, and first via conductors electrically connecting the first surface and the second surface and exposed on the first side surface of the first substrate from the first surface to the second surface.

